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**Snap-Curing**  
**Solvent-Free, Void-Free**  
**< 20 ppm Ionics**  
**Silver Epoxy**  
**Conductive Die-Attach Paste**

**IDEAL FOR:**

In-line Die-Attach  
 Smaller Dies of 5 mm or less  
 Smaller Area Substrate and Component  
 Attaches

**DESCRIPTION:**

ME8418 is designed for automated, inline processing. This single component, silver filled paste is solvent free, and electrically and thermally conductive. It is highly thixotropic with outstanding compatibility for bonding different adherends. The higher Tg and modulus made it more suitable for bonding smaller devices only. Wire-bonding at temperatures as high as 250°C is permissible.

ME8418 has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes.

**AVAILABILITY:**

ME8418 is available in syringes for automatic needle dispense applications or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw to ambient temperature for 30 minutes before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to the recommended schedule.

**PRIMA-SOLDER**  
**ME8418**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 5 min )	<4x10 <sup>-4</sup> ohm-cm
Dielectric Strength (Volts/mil)	>Not Applicable
Glass Transition Temp.(°C)	80 ±10%
Current Carrying Capabilities	20 Amp/mm <sup>2</sup>
Lap-Shear Strength	>NA
Device Push-off Strength	>1200 psi >8.3 N/mm <sup>2</sup>
Hardness (Type)	80 ( D ) ±10%
Cured Density (gm/cc)	3.5 ±10%
Thermal Conductivity	30 Btu-in/hr-ft <sup>2</sup> -°F ±10% 4.3 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	40 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	6 days
Avg. Viscosity(5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	60,000 cp ±20%
Thixotropic Index	

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

Temperature	Time	Pressure
150-160°C	60 sec	
125°C	5 min	
80°C	30 min	
60°C	8 hr	

**SHELF LIFE:**

Storage temperature	Shelf Life
-40°C	1 yr
20°C	6 da

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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